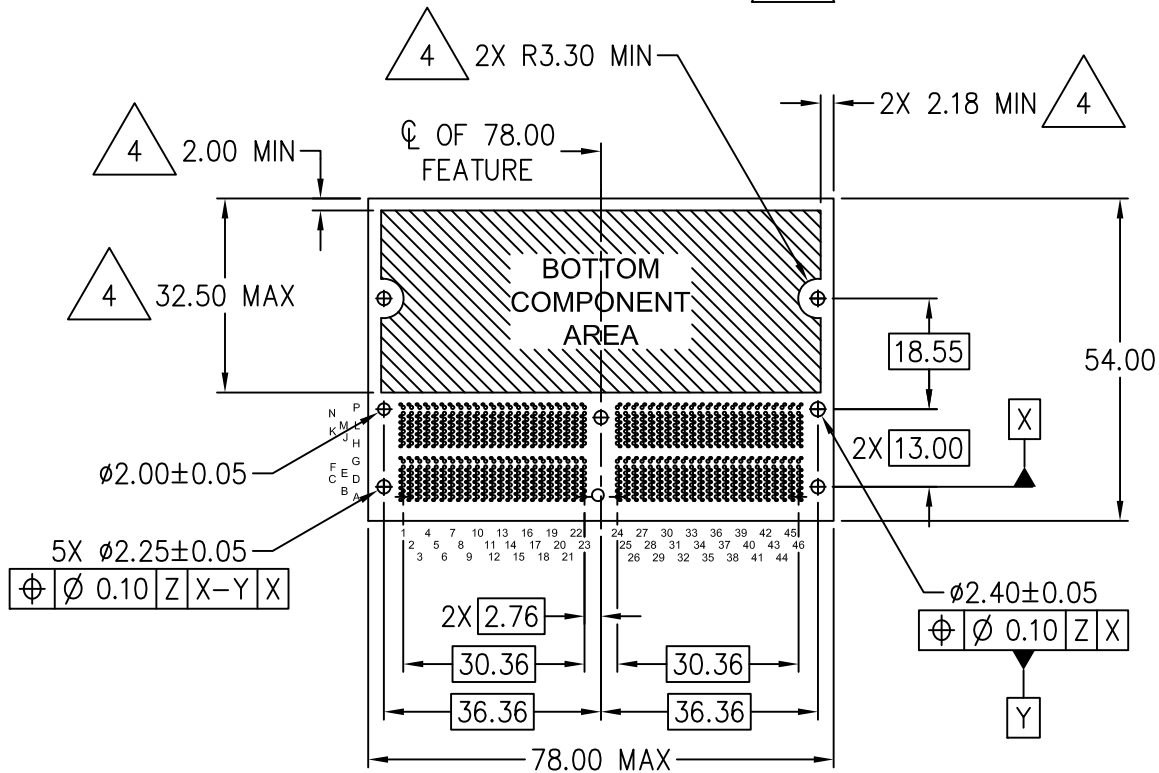
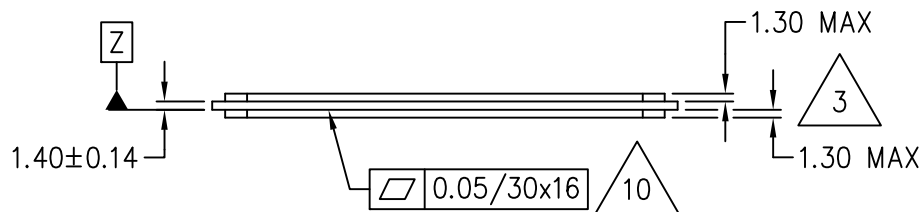
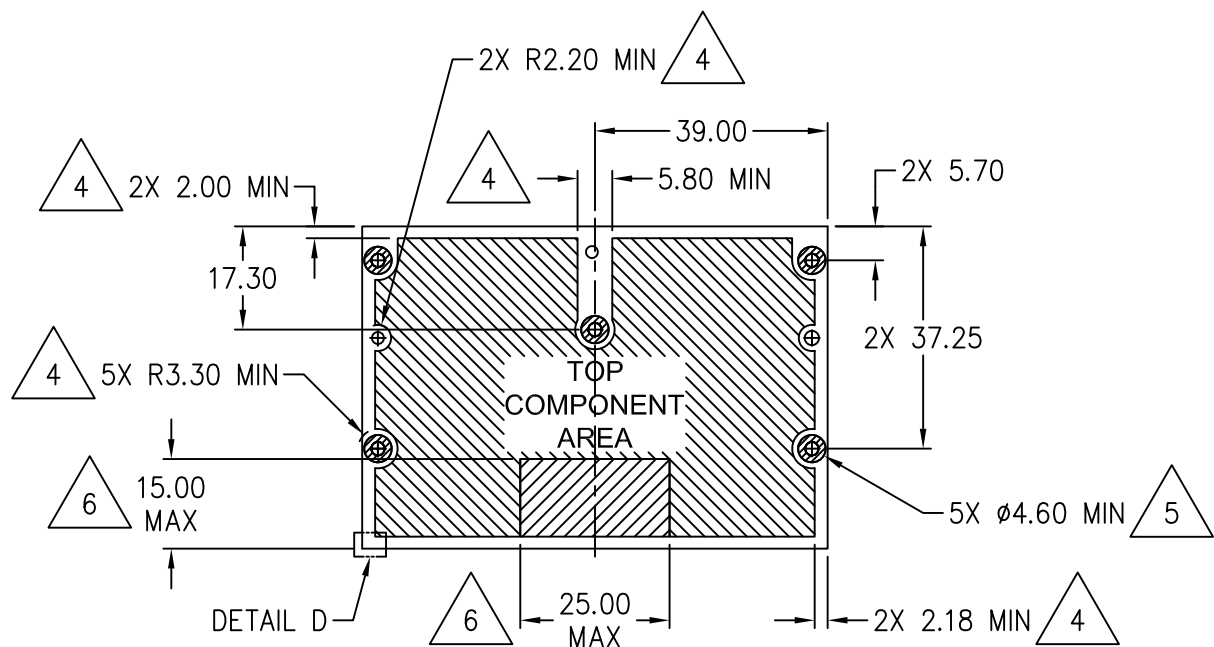




THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR

SHEET  
1 OF 10

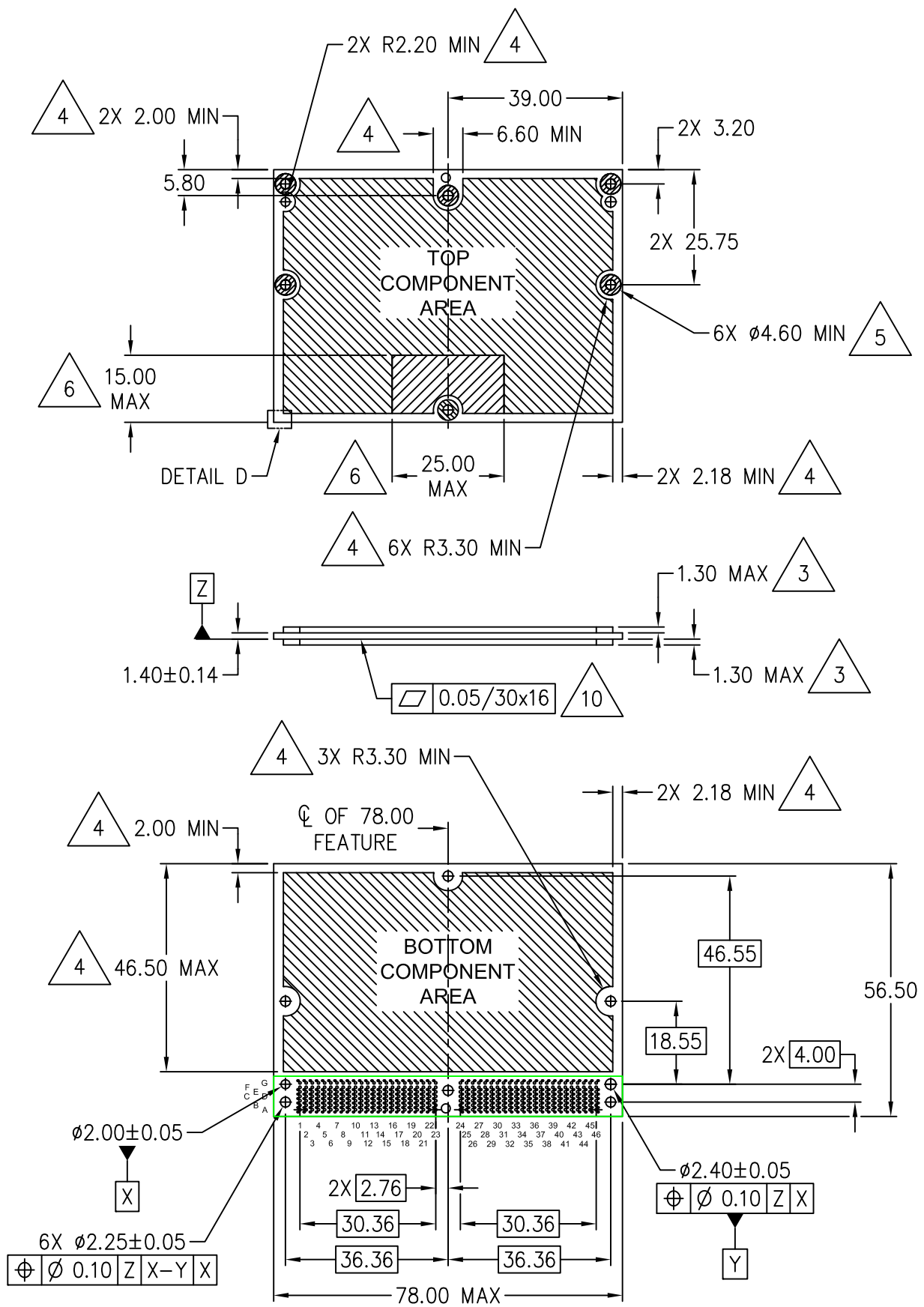


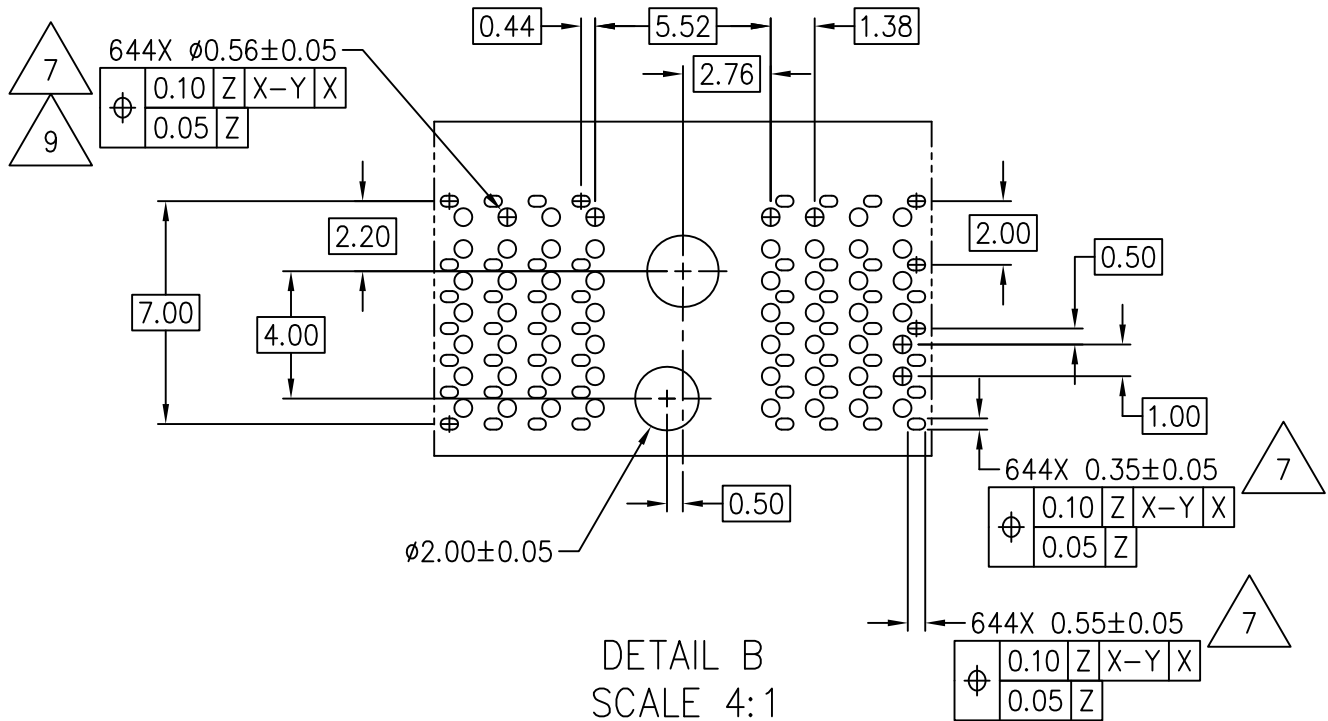
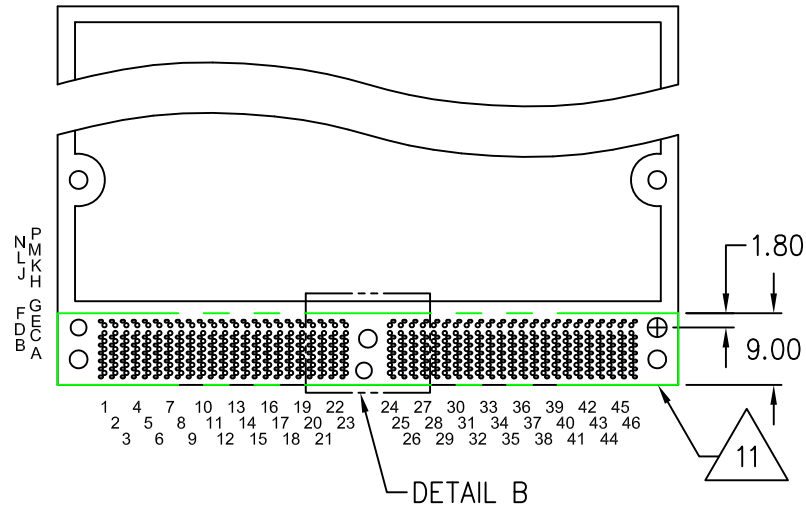
VARIATION BXXX



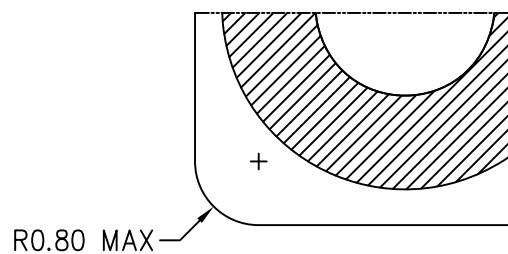
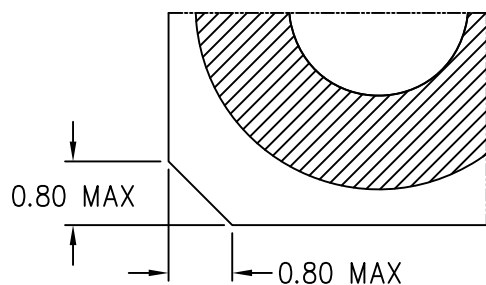




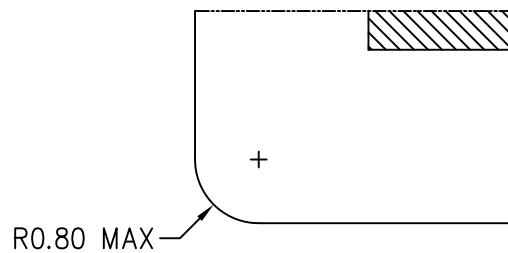
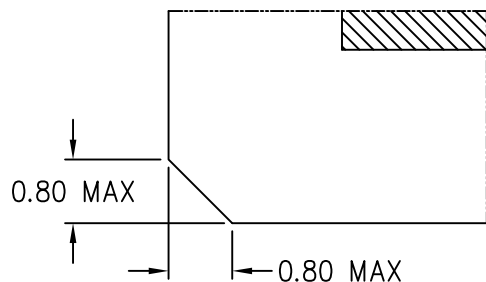




DETAILED REFERENCE PCB FOOTPRINT  
(APPLY TO VARIATION: DXXX/EXXX)



DETAIL C



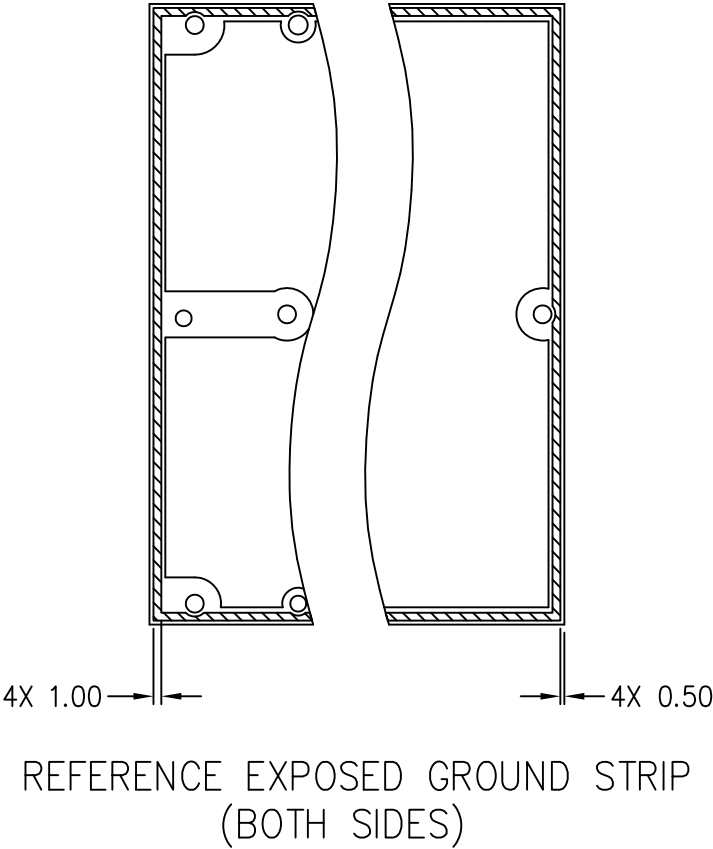
DETAIL D

DETAIL C AND D, TYP ALL CORNERS  
ANY COMBINATION OF CHAMFER AND RADII CAN BE USED



NOTES:

- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5–2009.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS, TOLERANCES ON ALL DIMENSIONS IS  $\pm 0.15$  UNLESS OTHERWISE SPECIFIED.
- 3. DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON THE MODULE.
- 4. BORDER OF COMPONENT AREA.
- 5. BORDER OF VSS NET FOR MODULE RETENTION.
- 6. THE DIMENSION DEFINE THE BOUNDARY OF PMIC AND SPD FOR THERMAL DESIGN.
- 7. SURFACE TERMINAL (A.K.A. CONTACT PAD).
- 8. RESERVED TO ATTACH RFI/EMI SHIELD (APPLY TO VARIATION: AXXX, BXXX, CXXX, DXXX AND EXXX).



NOTES CONTINUED:

9

PLATING FOR CONTACT TERMINALS ARE:

1) VARIATION Axxx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 0.25  
MICROMETERS MINIMUM PALLADIUM OVER 2.00  
MICROMETERS MINIMUM NICKEL.

2) VARIATION Bxxx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 2.00  
MICROMETERS MINIMUM NICKEL.

MODULE PLATING RECOMMENDATIONS TESTED PER INDUSTRY STANDARD EIA 364-1000.  
RELIABILITY TESTING REQUIRES TEST MODULE, CONNECTOR, AND IDENTIFICATION OF  
TEST CONDITIONS.

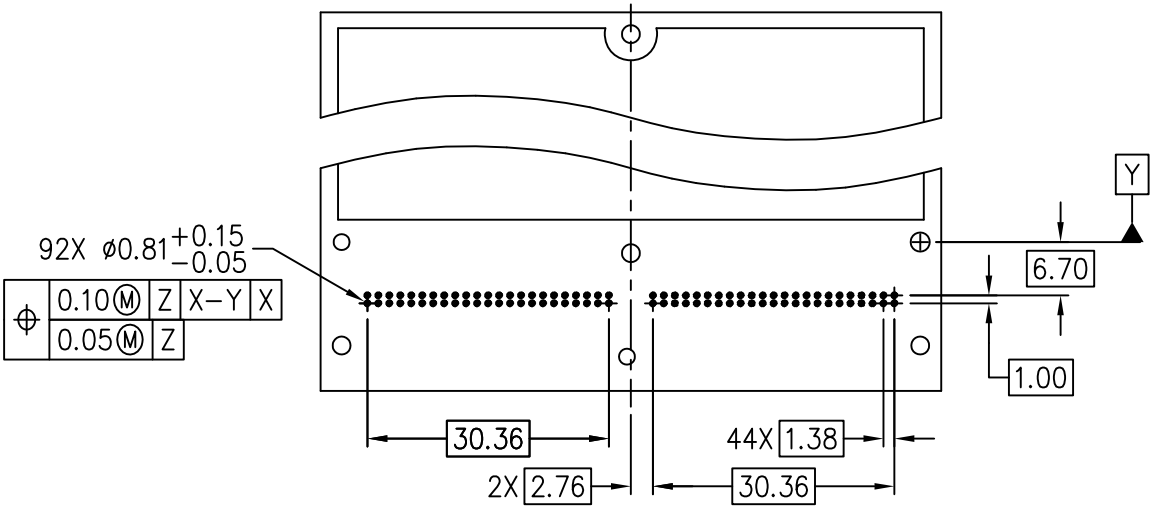
10

ONLY APPLIES TO THE CONTACT TERMINAL AREA.

11

SOLDER MASK IS NOT ALLOWED IN THIS AREA ON THE BOTTOM COMPONENT SIDE.

12. VOID METAL WITHIN AREA OF  $\phi 0.81$  CIRCLES ON THE BOTTOM LAYER WHERE CONNECTOR  
TERMINALS COULD BE PRESENT.



STP (3D) FILE RECORD

3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
MO-358A-AXXX_XBMA-N644_I1p0_R78p0x40p0Z4p14	SEP 2023	14-218
MO-358A-BXXX_XBMA-N644_I1p0_R78p0x54p0Z4p14	SEP 2023	14-218
MO-358A-CXXX_XBMA-N644_I1p0_R78p0x68p0Z4p14	SEP 2023	14-218
MO-358B-DXXX_XBMA-N322_I1p0_R78p0x28p5Z4p14	JUN 2024	14-229
MO-358B-EXXX_XBMA-N322_I1p0_R78p0x56p5Z4p14	JUN 2024	14-229

## TASK GROUP CONTRIBUTORS

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CHANGXIN MEMORY TECHNOLOGIES INC  
(CXMT)  
DELL INC  
FOXCONN INTERCONNECT TECHNOLOGY  
HEWLETT PACKARD ENTERPRISE  
HP INC  
INTEL CORPORATION  
LENOVO  
LOTES CO, LTD  
LUXSHARE-ICT, INC.  
MOLEX LLC  
SAMSUNG SEMICONDUCTOR  
SHENZHEN DEREN ELECTRONIC CO.  
LTD.  
SMART MODULAR TECHNOLOGIES INC.  
TE CONNECTIVITY  
WLCO SHENZHEN CO., LTD.

# CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE:A	DATE:SEPTEMBER 2023	ITEM NUMBER:14-218
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CHANGE RECORD HISTORY:
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INITIAL ISSUE:B	DATE:JUNE 2024	ITEM NUMBER:14-229
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LOCATION:	CHANGED FROM:	CHANGED TO:
SHEET 3	46.55	46.55
SHEETS 4 & 7		ADDED 2.20 DIMENSION
		ADDED SOLDER MASK KEEPOUT DIMENSIONS
SHEET 5	19.00 MAX 29.50	18.50 MAX 28.50
SHEET 6		ADDED ADDITIONAL HOLE AT 46.55 FROM DATUM Y
	5X Ø4.60 MIN	6X Ø4.60 MIN
	5X R3.30 MIN	6X R3.30 MIN
	5X Ø2.25±0.05	6X Ø2.25±0.05
	2X R3.30 MIN	3X R3.30 MIN
	46.00 MAX COMPONENT AREA	46.50 MAX COMPONENT AREA
SHEET 8		NEW SHEET FOR DETAILS
SHEET 10		ADDED NOTES 9, 10, 11, & 12

JEDEC SOLID STATE PRODUCT OUTLINE Copyright © 2024 JEDEC	TITLE DDR5 CAMM2, 1.00 MM X 1.38 MM PITCH MICROELECTRONIC ASSEMBLY	NUMBER MO-358	ISSUE B	DATE JUN 2024	SHEET iii
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